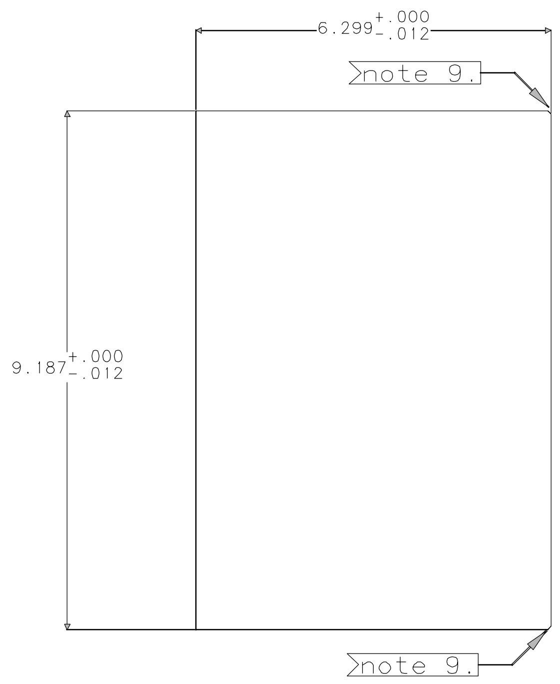
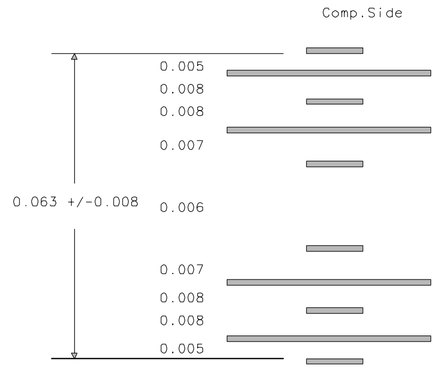
DWG. NO. A - 2591 SH REV. A





Layer Order
1.Signal_1 Microstrip
2.Power: +3.3V, +5Van
3.Signal_2 Stripline
4.Power: DGND, AGND
5.Signal_3
8.Signal_4
9.Power: DGND, AGND
10.Signal_5
11.Power:-5Van
12.Signal_6

Board Characteristics

0. All dimensions are given in inches unless specified otherwise.
1. Material FR4 with Tg>170C, E.g. FR406

3. Minimum trace width and clearence: 0.005".
4. 1 oz copper for all power layers and for Signal_1,2 (Top and Bottom)
   1/2 oz copper for Stripline trace layers (Signal_2,3,4,5).

5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
   Apply Solder Mask over bare copper.
6. Board Thickness: 0.063 +/- 0.008

8. Silkscreen on Component and Solder Sides.
9. 45 degree chamfer.
10. FHS tolerances: +/- 0.002 unless specified otherwise.
11. Interlayer spacing as specified

12. Zc=55 Ohm +/- 5 Ohm for 0.005" stripline and 0.006' microstrip traces on all layers.
    Perform TDR test for all signal layers.
    Present TDR test results for all signal layers.

13. Present plots for inspection before making boards.

BOARD's DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.014	3412	YES	---	
⊞	.041	553	YES	---	
⦶	.042	20	YES	---	
⊟	.057	10	YES	---	
⊖	.1023622	4	NO	---	
◫	.106	6	NO	---	
⊕	.125	4	YES	---	
□	.16	4	YES	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE:
FRACTIONS DECIMALS ANGLES
.XX
.XXX
DO NOT SCALE DRAWING
TREATMENT
FINISH
SIMILAR TO | ACT. WT | CALC WT

CONTRACT NO.

APPROVALS		DATE
DRAWN	M.Bogdan	9/1/06
CHECKED	M.Bogdan	9/1/06
ISSUED		

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE
QUIET-PreAmp Board
Specification Drawing

SIZE B | FSCM NO. | DWG. NO. A - 2591 | REV. A
SCALE 1/2 | SHEET

THIS SHEET IS COMPUTER GENERATED